

L Number	Hits	Search Text	DB	Time stamp
1	1055	438/127.icls,ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/19 16:38
2	12	438/127.icls,ccls. and (lead near6 ring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/19 17:55
3	16	5807768.URPN.	USPAT	2004/08/19 17:32
4	7	("4026008"   "4048356"   "4769344"   "5173766"   "5206794"   "5406117"   "5434105").PN.	USPAT	2004/08/19 17:35
5	46	438/127.icls,ccls. and (lead near6 dam)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/19 17:40
6	45	(438/127.icls,ccls. and (lead near6 dam)) not (438/127.icls,ccls. and (lead near6 ring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/19 17:40
7	1	5989942.URPN.	USPAT	2004/08/19 17:53
8	16475	(lead near6 ring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/19 17:55
9	576	(( (lead near6 ring)) near12 (encapsulant encasulat\$3 resin epoxy plastic polymer organic sealant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/19 18:04
10	362	(( (lead near6 ring)) near12 (encapsulant encasulat\$3 resin epoxy plastic polymer organic sealant)) and (within confin\$3 enclos\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/19 17:59
11	175	(( (lead near6 ring)) near12 (encapsulant encasulat\$3 resin epoxy plastic polymer organic sealant)) and (within confin\$3 enclos\$3)) and (chip die (integrated adj circuit) semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/19 18:05
12	35	(( (lead near6 ring)) near12 (encapsulant encasulat\$3 resin epoxy plastic polymer organic sealant)) near12(within confin\$3 enclos\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/19 17:59
13	35	(( (lead near6 ring)) near12 (encapsulant encasulat\$3 resin epoxy plastic polymer organic sealant)) near12 (within confin\$3 enclos\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/19 17:59
14	773	(( (lead near6 ring)) near12 (encapsulant encasulat\$3 resin epoxy plastic polymer organic sealant mold\$3 mould\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/19 18:05
15	320	(( (lead near6 ring)) near12 (encapsulant encasulat\$3 resin epoxy plastic polymer organic sealant mold\$3 mould\$3)) and (chip die (integrated adj circuit) semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/19 18:05

16	300	((( (lead near6 ring)) near12 (encapsulant encasulat\$3 resin epoxy plastic polymer organic sealant mold\$3 mould\$3)) and (chip die (integrated adj circuit) semiconductor)) not ((( (lead near6 ring)) near12 (encapsulant encasulat\$3 resin epoxy plastic polymer organic sealant)) near12 (within confin\$3 enclos\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/19 18:06
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